FOR IMMEDIATE RELEASE

STATS ChipPAC Receives Top 20 Semiconductor Manufacturing Patent Ranking for Fourth Consecutive Year

Singapore – 17 December 2014 – STATS ChipPAC Ltd. ("STATS ChipPAC" or the "Company" – SGX-ST: STATSChP), a leading provider of advanced semiconductor packaging and test services, announced today that it has been ranked for the fourth consecutive year among the world's top 20 semiconductor manufacturing companies in the Patent Power Scorecards published by the Institute of Electrical and Electronics Engineers (IEEE), the world's largest professional association for the advancement of technology.

The 2014 Patent Power Scorecards are based on an analysis of U.S. Patent and Trademark Office records through the end of 2013. The patent portfolios of more than 6,000 leading commercial enterprises, academic institutions, nonprofit organizations, and government agencies worldwide were reviewed and benchmarked by 1790 Analytics, an Intellectual Property (IP) evaluation firm. Organizations were measured by the size of their patent portfolio, level of activity for the year and quality of the patent portfolio in terms of growth, impact, originality and general applicability.

STATS ChipPAC is the only Outsourced Semiconductor Assembly and Test (OSAT) service provider ranked among the top 20 companies in the Semiconductor Manufacturing category. STATS ChipPAC has been the leading U.S. patent holder among OSAT providers worldwide since 2011. In total, STATS ChipPAC has been granted more than 1,300 patents by the U.S. Patent and Trademark Office (USPTO), of which 246 issued patents were evaluated for the 2014 Patent Power Scorecard. STATS ChipPAC has built up a patent portfolio in which advanced or future technologies comprise more than 60% of its IP, significantly higher than other OSATs in the industry.

"Technology and manufacturing innovations are essential in providing our customers with the advanced packaging and test solutions they need to address complex, rapidly changing product requirements. Our depth of knowledge and constant drive for innovation have been instrumental in helping our customers launch a number of exciting new products in their markets," said Dr. Han Byung Joon, Executive Vice President and Chief Technology Officer, STATS ChipPAC. "What differentiates our IP development is the focus we have on advanced technologies such as wafer level packaging, flip chip interconnect and 2.5D/3D integration which provide strategic value to our customers."

Forward-looking Statements

Certain statements in this release are forward-looking statements that involve a number of risks and uncertainties that could cause actual results to differ materially from those described in this release. Factors that could cause actual results to differ include, but are not limited to, general business and economic conditions and the state of the semiconductor industry; prevailing market conditions; demand for end-use applications products such as communications equipment, consumer and multi-applications and personal computers; decisions by customers to discontinue outsourcing of test and packaging services; level of competition; our reliance on a small group of principal customers; our continued success in technological innovations; pricing pressures, including declines in average selling prices; intellectual property rights disputes and litigation; our ability to control operating expenses; our substantial level of indebtedness and access to credit markets; potential impairment charges; availability of

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financing; changes in our product mix; our capacity utilisation; delays in acquiring or installing new equipment; limitations imposed by our financing arrangements which may limit our ability to maintain and grow our business; returns from research and development investments; changes in customer order patterns; customer credit risks; disruption of our operations; shortages in supply of key components and disruption in supply chain; inability to consolidate our Malaysia operations into our China operations and uncertainty as to whether such plan will achieve the expected objectives and results; loss of key management or other personnel; defects or malfunctions in our testing equipment or packages; rescheduling or cancelling of customer orders; adverse tax and other financial consequences if the taxing authorities do not agree with our interpretation of the applicable tax laws; classification of our Company as a passive foreign investment company; our ability to develop and protect our intellectual property; changes in environmental laws and regulations; exchange rate fluctuations; regulatory approvals for further investments in our subsidiaries; majority ownership by Temasek Holdings (Private) Limited ("Temasek") that may result in conflicting interests with Temasek and our affiliates; unsuccessful acquisitions and investments in other companies and businesses; labour union problems in South Korea; uncertainties of conducting business in China and changes in laws, currency policy and political instability in other countries in Asia; natural calamities and disasters, including outbreaks of epidemics and communicable diseases; the continued trading and listing of our ordinary shares on the Singapore Exchange Securities Trading Limited ("SGX-ST"). You should not unduly rely on such statements. We do not intend, and do not assume any obligation, to update any forward-looking statements to reflect subsequent events or circumstances.

About STATS ChipPAC Ltd.
STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

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